



**OPA137**  
**OPA2137**  
**OPA4137**

## LOW COST FET-INPUT OPERATIONAL AMPLIFIERS *MicroAmplifier™ Series*

### FEATURES

- **FET INPUT:**  $I_B = 5\text{pA}$
- **LOW OFFSET VOLTAGE:** 1.5mV
- **WIDE SUPPLY RANGE:**  $\pm 2.25\text{V}$  to  $\pm 18\text{V}$
- **LOW QUIESCENT CURRENT:** 220 $\mu\text{A}$ /channel
- **EXCELLENT SPEED/POWER:** 1MHz
- **INPUT TO POSITIVE SUPPLY**
- **MicroSIZE PACKAGES:** SOT-23-5, MSOP-8
- **SINGLE, DUAL, AND QUAD**

### APPLICATIONS

- **STRAIN GAGE AMPLIFIER**
- **PHOTODETECTOR AMPLIFIER**
- **PRECISION INTEGRATOR**
- **BATTERY-POWERED INSTRUMENTS**
- **TEST EQUIPMENT**
- **ACTIVE FILTERS**

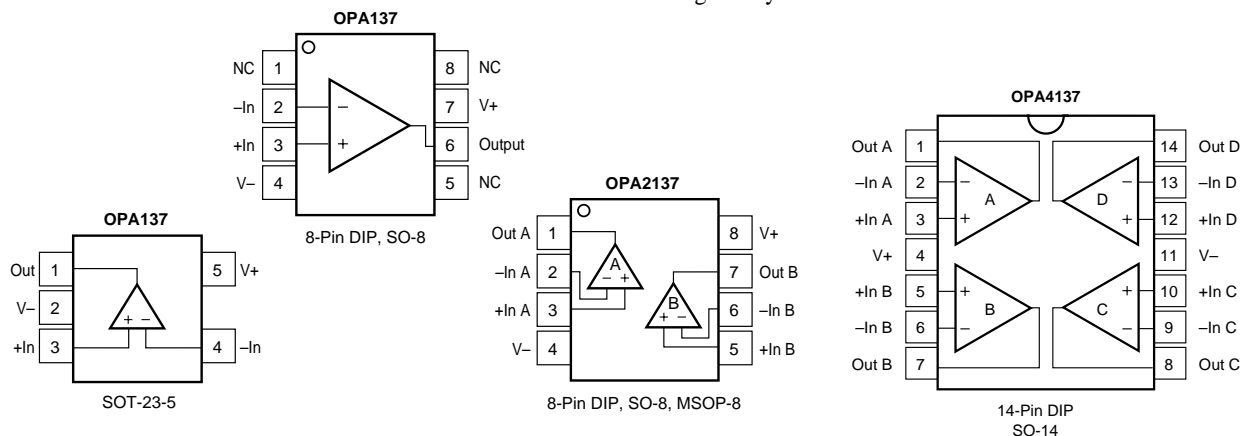
### DESCRIPTION

OPA137 series FET-input operational amplifiers are designed for low cost and miniature applications. In addition to small size (SOT-23-5 and MSOP-8 packages), they provide low input bias current (5pA), low quiescent current (220 $\mu\text{A}$ /channel), and high open-loop gain (94dB).

Either single (+4.5V to +36V) or dual ( $\pm 2.25$  to  $\pm 18\text{V}$ ) supplies can be used. The input common-mode voltage range includes the positive supply—suitable for many single-supply applications. Single, dual, and quad versions have identical specifications for maximum design flexibility.

OPA137 op amps are easy to use and free from phase inversion and overload problems found in some FET-input amplifiers. High performance, including linearity, is maintained as the amplifiers swing to their specified limits. In addition, the combination of high slew rate (3.5V/ $\mu\text{s}$ ) and wide bandwidth (1MHz) provide fast settling time assuring good dynamic response. Dual and quad designs feature completely independent circuitry for lowest crosstalk and freedom from interaction.

The single (OPA137) packages are the tiny 5-lead SOT-23-5 surface mount, SO-8 surface mount, and 8-pin DIP. The dual (OPA2137) comes in the miniature MSOP-8 surface mount, SO-8 surface mount, and 8-pin DIP packages. The quad (OPA4137) packages are the SO-14 surface mount and the 14-pin DIP. All are specified from  $-40^\circ\text{C}$  to  $+85^\circ\text{C}$  and operate from  $-55^\circ\text{C}$  to  $+125^\circ\text{C}$ . A SPICE macromodel is available for design analysis.



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# SPECIFICATIONS: $V_S = \pm 15V$

At  $T_A = +25^\circ C$ ,  $R_L = 10k\Omega$  connected to ground, unless otherwise noted.

**Boldface** limits apply over the specified temperature range,  $T_A = -40^\circ C$  to  $+85^\circ C$ .

PARAMETER	CONDITION	OPA137N, U, P OPA2137E, U, P OPA4137U, P			OPA137NA, UA, PA OPA2137EA, UA, PA OPA4137UA, PA			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>OFFSET VOLTAGE</b> Input Offset Voltage $V_{OS}$ $T_A = -40^\circ C$ to $+85^\circ C$ vs Temperature $dV_{OS}/dT$ vs Power Supply PSRR $T_A = -40^\circ C$ to $+85^\circ C$ Channel Separation (dual, quad)	$T_A = -40^\circ C$ to $+85^\circ C$ $V_S = \pm 3V$ to $\pm 18V$ dc		$\pm 1.5$ $\pm 2.5$ $\pm 15$ $\pm 90$ 0.6	$\pm 3$ $\pm 7$ $\pm 250$ <b><math>\pm 250</math></b>		$\pm 2.5$ $\pm 3.5$ * * *	$\pm 10$ <b><math>\pm 15</math></b> * * *	mV mV $\mu V/^\circ C$ $\mu V/V$ $\mu V/V$
<b>INPUT BIAS CURRENT</b> Input Bias Current $I_B$ vs Temperature Input Offset Current $I_{OS}$	$V_{CM} = 0V$		See Typical Curve $\pm 5$ $\pm 2$	$\pm 100$ $\pm 50$		* * *	* * *	pA pA
<b>NOISE</b> Input Voltage Noise, $f = 0.1$ to $10Hz$ Input Voltage Noise Density, $f = 1kHz$ $e_n$ Current Noise Density, $f = 1kHz$ $i_n$			2 45 1.2			* * *		$\mu Vp-p$ $nV/\sqrt{Hz}$ $fA/\sqrt{Hz}$
<b>INPUT VOLTAGE RANGE</b> Common-Mode Voltage Range $V_{CM}$ Common-Mode Rejection Ratio CMRR OPA137, OPA2137 OPA4137 $T_A = -40^\circ C$ to $+85^\circ C$ OPA137, OPA2137 OPA4137	$V_{CM} = -12V$ to $15V$  $V_{CM} = -12V$ to $15V$	$(V-) + 3$   <b>72</b> <b>70</b>	 84 84	$(V+)$   <b>70</b> <b>70</b>	*   <b>70</b> <b>70</b>	* * *	*   <b>70</b> <b>70</b>	V dB dB dB
<b>INPUT IMPEDANCE</b> Differential Common-Mode			$10^{10} \parallel 1$ $10^{12} \parallel 2$			* *		$\Omega \parallel pF$ $\Omega \parallel pF$
<b>OPEN-LOOP GAIN</b> Open-Loop Voltage Gain $A_{OL}$ $T_A = -40^\circ C$ to $+85^\circ C$	$V_O = -13.8V$ to $13.9V$ $V_O = -13.8V$ to $13.9V$	86 <b>86</b>	94		* *	* *		dB dB
<b>FREQUENCY RESPONSE</b> Gain-Bandwidth Product GBW Slew Rate SR Settling Time, 0.1% 0.01% Overload Recovery Time Total Harmonic Distortion + Noise THD+N	$G = 1$ $G = 1, 10V$ Step, $C_L = 100pF$ $G = 1, 10V$ Step, $C_L = 100pF$ $V_{IN} * G = V_S$ $G = 1, f = 1kHz, 3.5V_{rms}$		1 3.5 8 10 1 0.05			* * * * * *		MHz $V/\mu s$ $\mu s$ $\mu s$ $\mu s$ %
<b>OUTPUT</b> Voltage Output $V_{OUT}$ $T_A = -40^\circ C$ to $+85^\circ C$ Short-Circuit Current $I_{SC}$ Capacitive Load Drive $C_{LOAD}$		$(V-) + 1.2$ <b><math>(V-) + 1.2</math></b>	 $-25/+60$ 1000	$(V+) - 1.1$ <b><math>(V+) - 1.1</math></b>	* *	* *	* *	V V mA pF
<b>POWER SUPPLY</b> Specified Operating Range $V_S$ Operating Voltage Range Dual Supplies Single Supply Quiescent Current $I_Q$ $T_A = -40^\circ C$ to $+85^\circ C$	$I_O = 0$ $I_O = 0$	$\pm 2.25^{(1)}$ +4.5	$\pm 15$  $\pm 220$	$\pm 18$ +36 $\pm 270$ <b><math>\pm 375</math></b>	* *	* *	* * * *	V V V $\mu A$ $\mu A$
<b>TEMPERATURE RANGE</b> Specified Range Operating Range Storage Range Thermal Resistance $\theta_{JA}$ SOT-23-5 Surface Mount MSOP-8 Surface Mount SO-8 Surface Mount 8-Pin DIP SO-14 Surface Mount 14-Pin DIP		-40 -55 -55		+85 +125 +125	* * *		* * *	$^\circ C$ $^\circ C$ $^\circ C$ $^\circ C/W$ $^\circ C/W$ $^\circ C/W$ $^\circ C/W$ $^\circ C/W$ $^\circ C/W$

\* Specifications the same as OPA137N, U, P.

NOTE: (1) At minimum power supply voltage inputs must be biased above ground in accordance with common-mode voltage range restrictions—see “Operating Voltage” discussion.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Supply Voltage, V+ to V- .....	36V
Input Voltage .....	(V-) -0.7V to (V+) +0.7V
Input Current .....	2mA
Output Short-Circuit <sup>(2)</sup> .....	Continuous
Operating Temperature .....	-55°C to +125°C
Storage Temperature .....	-55°C to +125°C
Junction Temperature .....	+150°C
Lead Temperature (soldering, 10s) .....	300°C

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum ratings for extended periods may affect device reliability. (2) Short circuit to ground, one amplifier per package.



## ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## PACKAGE/ORDERING INFORMATION

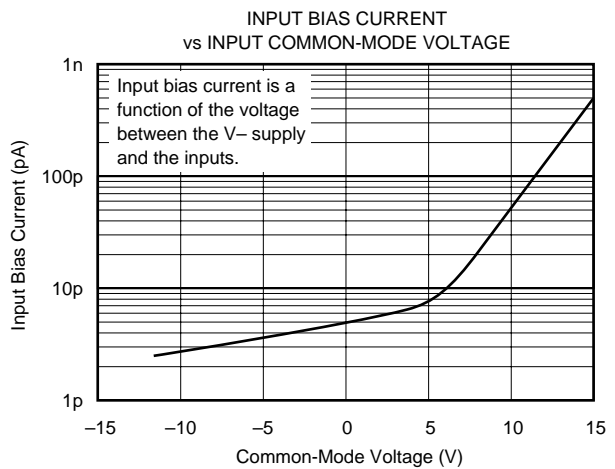
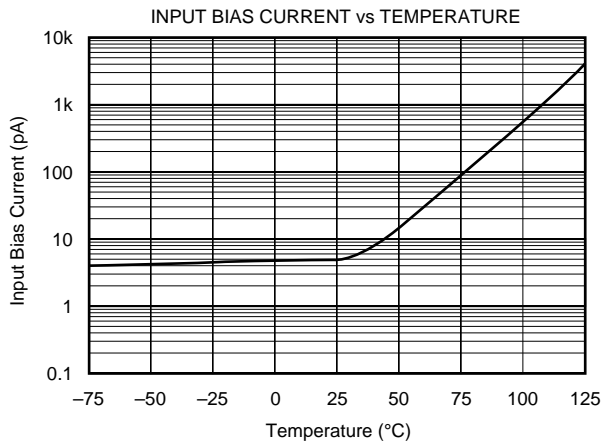
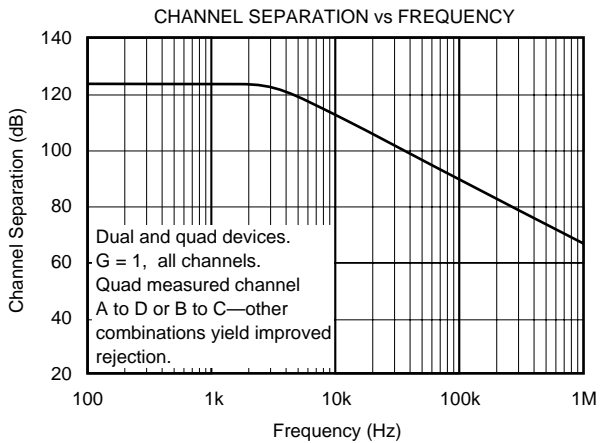
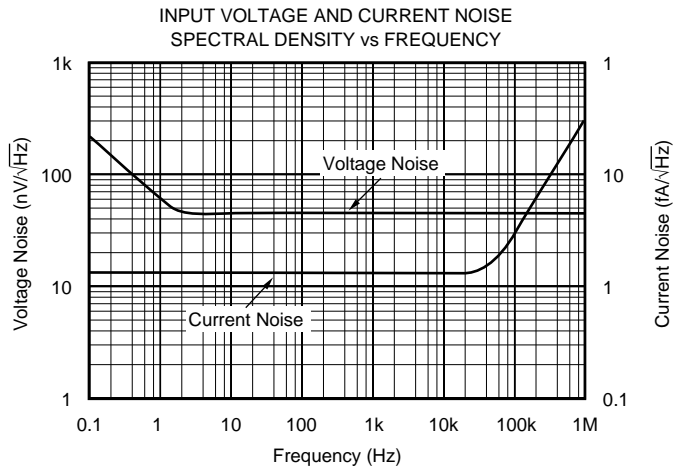
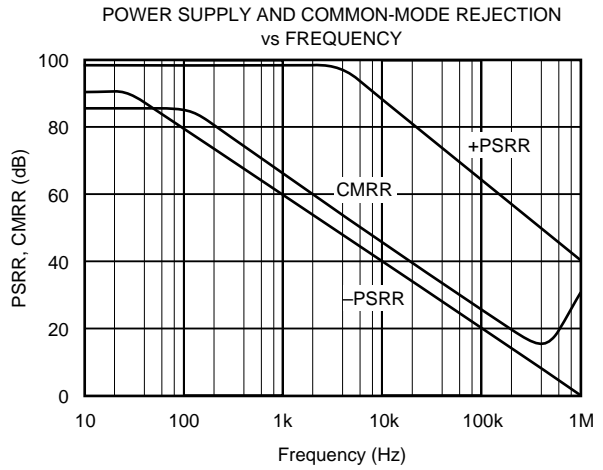
PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER <sup>(1)</sup>	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER <sup>(2)</sup>	TRANSPORT MEDIA
<b>Single</b>						
OPA137N	5-Lead SOT-23-5 Surface Mount	331	-40°C to +85°C	E37 <sup>(3)</sup>	OPA137N/250	Tape and Reel
"	"	"	"	"	OPA137N/3K	Tape and Reel
OPA137NA	5-Lead SOT-23-5 Surface Mount	331	-40°C to +85°C	E37 <sup>(3)</sup>	OPA137NA/250	Tape and Reel
"	"	"	"	"	OPA137NA/3K	Tape and Reel
OPA137U	SO-8 Surface Mount	182	-40°C to +85°C	OPA137U	OPA137U	Rails
"	"	"	"	"	OPA137U/2K5	Tape and Reel
OPA137UA	SO-8 Surface Mount	182	-40°C to +85°C	OPA137UA	OPA137UA	Rails
"	"	"	"	"	OPA137UA/2K5	Tape and Reel
OPA137P	8-Pin DIP	006	-40°C to +85°C	OPA137P	OPA137P	Rails
OPA137PA	8-Pin DIP	006	-40°C to +85°C	OPA137PA	OPA137PA	Rails
<b>Dual</b>						
OPA2137E	MSOP-8 Surface Mount	337	-40°C to +85°C	E37 <sup>(3)</sup>	OPA2137E/250	Tape and Reel
"	"	"	"	"	OPA2137E/2K5	Tape and Reel
OPA2137EA	MSOP-8 Surface Mount	337	-40°C to +85°C	E37 <sup>(3)</sup>	OPA2137EA/250	Tape and Reel
"	"	"	"	"	OPA2137EA/2K5	Tape and Reel
OPA2137U	SO-8 Surface Mount	182	-40°C to +85°C	OPA2137U	OPA2137U	Rails
"	"	"	"	"	OPA2137U/2K5	Tape and Reel
OPA2137UA	SO-8 Surface Mount	182	-40°C to +85°C	OPA2137UA	OPA2137UA	Rails
"	"	"	"	"	OPA2137UA/2K5	Tape and Reel
OPA2137P	8-Pin DIP	006	-40°C to +85°C	OPA2137P	OPA2137P	Rails
OPA2137PA	8-Pin DIP	006	-40°C to +85°C	OPA2137PA	OPA2137PA	Rails
<b>Quad</b>						
OPA4137U	SO-14 Surface Mount	235	-40°C to +85°C	OPA4137U	OPA4137U	Rails
"	"	"	"	"	OPA4137U/2K5	Tape and Reel
OPA4137UA	SO-14 Surface Mount	235	-40°C to +85°C	OPA4137UA	OPA4137UA	Rails
"	"	"	"	"	OPA4137UA/2K5	Tape and Reel
OPA4137P	14-Pin DIP	010	-40°C to +85°C	OPA4137P	OPA4137P	Rails
OPA4137PA	14-Pin DIP	010	-40°C to +85°C	OPA4137PA	OPA4137PA	Rails

NOTES: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book. (2) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 3000 pieces of "OPA137NA/3K" will get a single 3000-piece Tape and Reel. For detailed Tape and Reel mechanical information, refer to Appendix B of Burr-Brown IC Data Book. (3) Grade information is marked on the reel.

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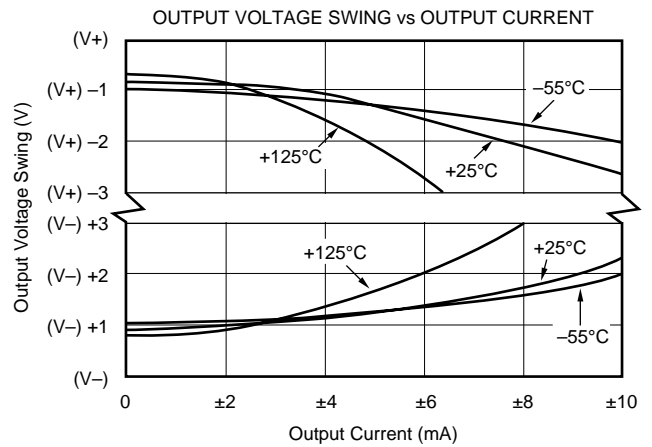
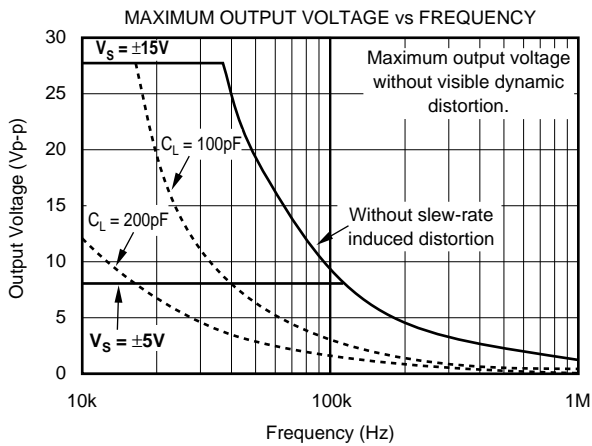
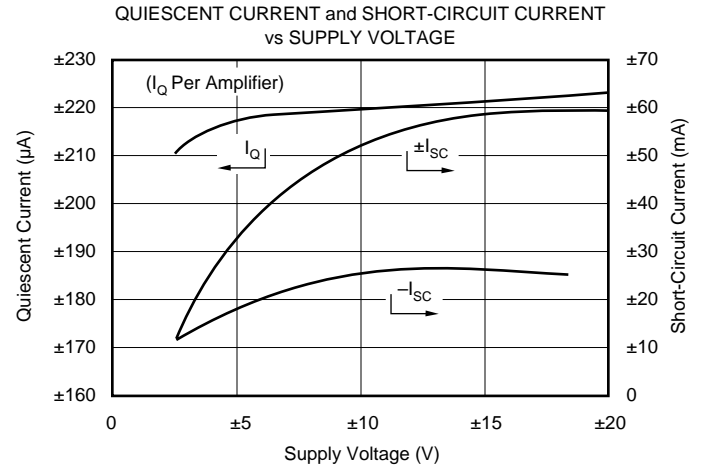
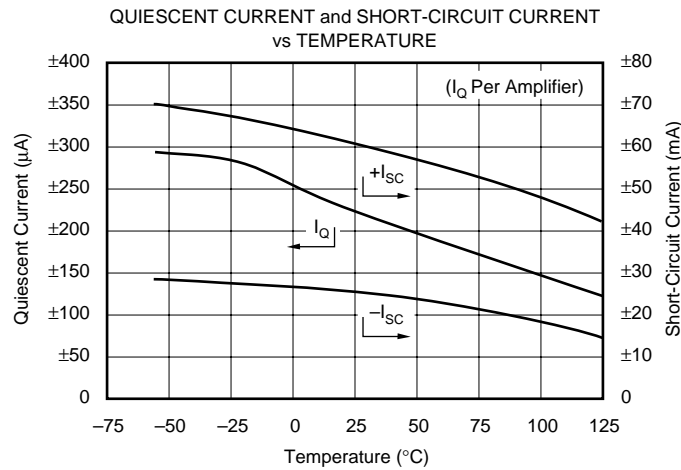
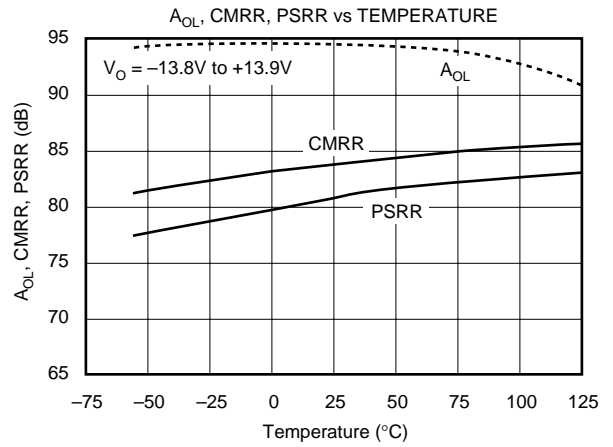
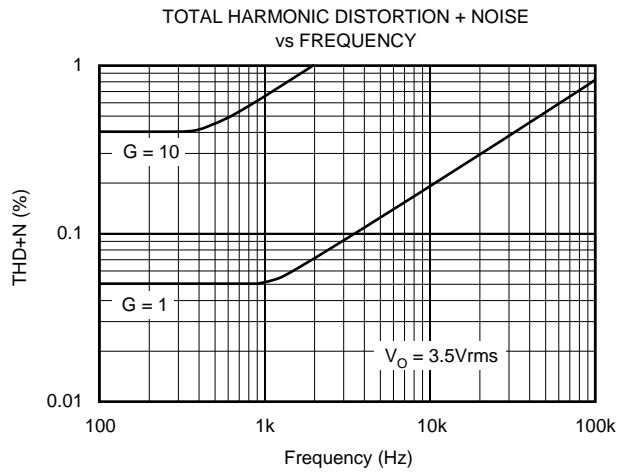
# TYPICAL PERFORMANCE CURVES

At  $T_A = +25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$ ,  $R_L = 10\text{k}\Omega$ , connected to ground, unless otherwise noted.



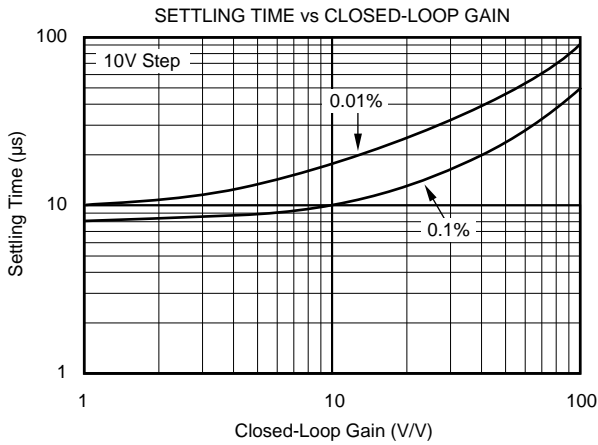
# TYPICAL PERFORMANCE CURVES (CONT)

At  $T_A = +25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$ ,  $R_L = 10\text{k}\Omega$ , connected to ground, unless otherwise noted.



# TYPICAL PERFORMANCE CURVES (CONT)

At  $T_A = +25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$ ,  $R_L = 10\text{k}\Omega$ , connected to ground, unless otherwise noted.



## APPLICATIONS INFORMATION

OPA137 series op amps are unity-gain stable and suitable for a wide range of general-purpose applications. Power supply pins should be bypassed with 10nF ceramic capacitors or larger. All circuitry is completely independent in dual and quad versions, assuring normal performance when one amplifier in a package is overdriven or short circuited. Many key parameters are guaranteed over the specified temperature range,  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ .

### OPERATING VOLTAGE

OPA137 op amps can be operated on power supplies as low as  $\pm 2.25\text{V}$ . Performance remains excellent with power supplies ranging from  $\pm 2.25\text{V}$  to  $\pm 18\text{V}$  ( $+4.5\text{V}$  to  $+36\text{V}$  single supply). Most parameters vary only slightly throughout this supply voltage range. Quiescent current and short-circuit current vs supply voltage are shown in Typical Performance Curves.

Operation at very low supply voltage ( $V_S \leq \pm 3\text{V}$ ) requires careful attention to ensure that the common-mode voltage remains within the linear range,  $V_{CM} = (V-)+3\text{V}$  to  $(V+)$ . Inputs may need to be biased above ground in accordance with the common-mode voltage range restrictions for linear operation.

### INPUT VOLTAGE

The input common-mode voltage range of OPA137 series op amps extends from  $(V-)+3\text{V}$  to the positive rail,  $V+$ . For normal operation, inputs should be limited to this range. The inputs may go beyond the power supplies without output phase-reversal. Many FET-input op amps (such as TL061 types) exhibit phase-reversal of the output when the input common-mode range is exceeded. This can occur in voltage-follower circuits, causing serious problems in control loop applications.

Input terminals are diode-clamped to the power supply rails for ESD protection. If the input voltage can exceed the negative supply by 500mV, input current should be limited to 2mA (or less). If the input current is not adequately limited, you may see unpredictable behavior in the other amplifiers in the package. This is easily accomplished with an input resistor as shown in Figure 1. Many input signals are inherently current-limited, therefore, a limiting resistor may not be required.

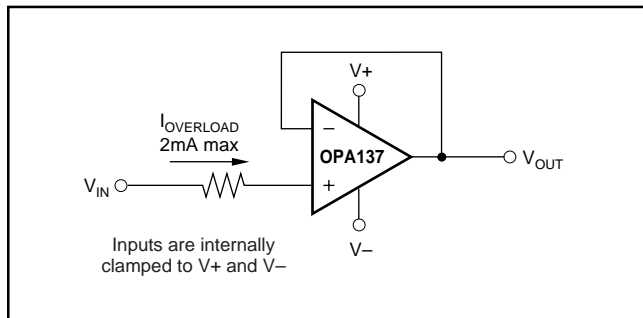


FIGURE 1. Input Current Protection for Voltages Exceeding the Supply Voltage.

## HIGH-SIDE CURRENT SENSING

Many applications require the sensing of signals near the positive supply. The common-mode input range of OPA137 op amps includes the positive rail, enabling them to be used to sense power supply currents as shown in Figure 2.



FIGURE 2. High-Side Current Monitor.

### INPUT BIAS CURRENT

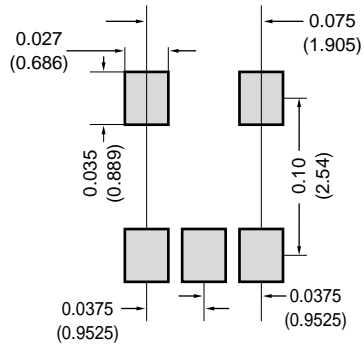
The input bias current is approximately 5pA at room temperature and increases with temperature as shown in the typical performance curve “Input Bias Current vs Temperature.”

Input Bias current also varies with common-mode voltage and power supply voltage. This variation is dependent on the voltage between the negative power supply and the common-mode input voltage. The effect is shown in the typical performance curve “Input Bias Current vs Common-Mode Voltage.”



FIGURE 3. Photodetector Amplifier.

**SOT-23-5**  
(Package Drawing #331)



**MSOP-8**  
(Package Drawing #337)



Refer to end of data sheet or Appendix C of Burr-Brown Data Book for tolerances and detailed package drawing. For further information on solder pads for surface-mount devices consult Application Bulletin AB-132.

FIGURE 4. Recommended SOT-23-5 and MSOP-8 Solder Footprints.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
OPA137N/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA137N/250E4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA137N/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA137N/3KE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA137NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA137NA/250E4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA137NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA137NA/3KE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
OPA137P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU SNPB	N / A for Pkg Type	
OPA137PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU SNPB	N / A for Pkg Type	
OPA137U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA137UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA137UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA137UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA137UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA137UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137E/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
OPA2137E/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137E/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137E/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137EA/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137EA/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA2137PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA2137PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA2137PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA2137U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137U/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA2137UA/2K5E4	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI	
OPA2137UAE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
OPA2137UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137P	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA4137PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA4137PAG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA4137PG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	
OPA4137U	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137U/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137U/2K5E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137UA/2K5	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137UA/2K5G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137UAE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
OPA4137UE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

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<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA137UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2137E/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137E/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2137U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2137UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4137U/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
OPA4137UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA137UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2137E/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2137E/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA2137EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2137EA/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA2137U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA2137UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA4137U/2K5	SOIC	D	14	2500	367.0	367.0	38.0
OPA4137UA/2K5	SOIC	D	14	2500	367.0	367.0	38.0

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